Title (en)

VIALESS INTEGRATED INDUCTIVE ELEMENTS FOR ELECTROMAGNETIC APPLICATIONS

Title (de)

INDUKTIVE ELEMENTE FÜR ELEKTROMAGNETISCHE ANWENDUNGEN OHNE KONTAKTLÖCHER

Title (fr)

ELEMENTS INDUCTIFS INTEGRES SANS TROUS D'INTERCONNEXIONS POUR DES APPLICATIONS ELECTROMAGNETIQUES

Publication

EP 1000442 A4 20000517 (EN)

Application

EP 98903872 A 19980130

Priority

- US 9801879 W 19980130
- US 79433897 A 19970203

Abstract (en)

[origin: WO9834287A1] An inductor suitable for integration in VLSI circuits and devices is fabricated by means of a post foundry procedure involving the deposition and patterning of layers of conductor material (32), isolation material (34), core material (50), isolation material (52) and conductor material (54) to produce conductive coils (60, 62) wrapped around a magnetic core without the need for vias. The fabrication steps utilize a combination of microelectronic and micromachining technologies.

IPC 1-7

H01L 43/02; H01F 41/04; H01F 17/00; H01L 23/64

IPC 8 full level

H01F 17/00 (2006.01); **H01L 21/822** (2006.01); **H01L 27/04** (2006.01)

CPC (source: EP KR)

H01F 17/0033 (2013.01 - EP); **H10N 50/80** (2023.02 - KR)

Citation (search report)

- [A] US 3881244 A 19750506 - KENDALL DON LESLIE
- [A] PATENT ABSTRACTS OF JAPAN vol. 017, no. 568 (E - 1447) 14 October 1993 (1993-10-14)
- See references of WO 9834287A1

Designated contracting state (EPC)

DE ES FR GB IT

DOCDB simple family (publication)

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DOCDB simple family (application)

US 9801879 W 19980130; AU 6052498 A 19980130; CA 2279297 A 19980130; EP 98903872 A 19980130; JP 53314298 A 19980130; KR 19997006982 A 19990803; TW 87101261 A 19980203